

REMARKS

This is in response to the Office Action dated March 23, 2005. In view of the foregoing amendments and following representations, reconsideration is respectfully requested.

Initially, the specification and abstract have been reviewed and revised, and a substitute specification and abstract has been prepared. No new matter has been added. Also enclosed is a "marked-up" copy of the original specification and abstract to show the changes that have been incorporated into the substitute specification and abstract. The enclosed copy is entitled "Version with Markings to Show Changes Made."

Next, on page 3 of the Office Action, claims 2 and 7 are objected to as being dependent upon a rejected base claim, but have been indicated to be allowable if rewritten in independent form including all of the limitations of the base claim and any intervening claims. Accordingly, claim 2 has been rewritten in independent form, thereby obviating the objection and placing claim 2 in allowable form.

Next, on page 2 of the Office Action, claims 1 and 3-6 are rejected under 35 U.S.C. § 102(b) as being anticipated by Haji et al. (USPN 6,350,664). Also, claims 8 and 9 are rejected under 35 U.S.C. § 103(a) as being unpatentable over Haji in view of Wood et al. (USPN 6,828,175).

To more clearly distinguish the claims over the applied prior art references, independent claims 1, 8 and 9 have been amended to recite that the electronic component is embedded into a base made of a resin sheet. As will be explained below, the amended independent claims now clearly distinguish over the applied prior art references.

Haji discloses a method of manufacturing a semiconductor device, which includes forming a resin layer 24 on a face of a semiconductor wafer 21'. The methods of forming resin layer are described in column 3, lines 18-46 of the Haji patent. In particular, two methods of forming the resin layer are described, i.e. a resin film adhering method and a resin coating method.

In the resin film adhering method, resin materials are coated with an adhesive on one surface and adhered on the semiconductor wafer 1. Subsequently, the adhesive is thermally cured to tightly bond the resin film with the semiconductor wafer. In the resin coating method, liquid resin is coated on the face of a semiconductor wafer 1 where the electrodes are disposed, and cured. The semiconductor wafer is then sent to a blind hole forming process to expose the surfaces of the electrodes 2.

Clearly, the methods disclosed in the Haji patent do not include an embedding operation in which the electronic component is embedded within a sheet of resin. As explained above, in Haji, the resin layer is "formed on" the semiconductor wafer 1 by the adhering method or the resin coating method. In

the present invention, however, it is unnecessary to form a resin layer on the face of the electronic component. Furthermore, in Haji, the object to be covered by the resin layer 24 is a semiconductor wafer 21'. Thus, the thickness of the semiconductor wafer is very thin and the thickness is very small relative to the electronic component-mounted components in the present invention. Accordingly, in Haji, it is not necessary to embed the semiconductor wafer 21' into the resin layer 24. And, if the semiconductor wafer were to be embedded into the resin layer, it is quite likely that the semiconductor wafer would break due to the thinness thereof.

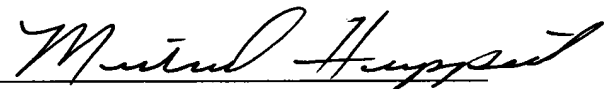
Wood is applied in combination with the Haji reference in the rejections of claims 8 and 9 to teach "stacking" components. However, the Wood reference does not disclose or suggest embedding an electronic component into a base formed of a resin sheet. Accordingly, it is submitted that the collective teachings of the Haji and Wood references do not meet each and every limitation of independent claims 1, 8 and 9.

In view of the above, it is submitted that the present application is now clearly in condition for allowance. The Examiner therefore is requested to pass this case to issue.

In the event that the Examiner has any comments or suggestions of a nature necessary to place this case in condition for allowance, then the Examiner is requested to contact Applicant's undersigned attorney by telephone to promptly resolve any remaining matters.

Respectfully submitted,

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